# CLAIMS

1. A conductive resin composition comprising:
an epoxy resin (A),
a compound (B) having a (meth)acryloyl group and a glycidyl group,
a phenolic resin curing agent (C),
a radical polymerization initiator (D) and
a conductive particle (E).

2. The conductive resin composition according to claim 1, wherein the number of moles of the (meth)acryloyl groups in the component (B) is 7 to 28 with respect to the number of moles of the glycidyl groups in the conductive resin composition taken as 100.

3. The conductive resin composition according to claim 1 or 2, further comprising a (meth)acrylate compound (F).

4. The conductive resin composition according to claim 3, wherein the total of the number of moles of the (meth)acryloyl groups in the component (B) and the number of moles of the (meth)acryloyl groups in the component (F) is 8 to 36 with respect to the number of moles of the glycidyl groups in the conductive resin composition taken as 100.

5. The conductive resin composition according to any one of claims 1 to 4, further comprising an amine curing catalyst (G).

6. The conductive resin composition according to any one of claims 1 to 5, wherein the component (A) is a liquid epoxy resin.

7. The conductive resin composition according to any one of claims 1 to 6, wherein the component (B) is a partially (meth)acrylated cresol novolak epoxy resin and/or a mono(meth)acrylated bisphenol epoxy resin.

8. A cured product obtainable by B-staging the conductive resin composition according to any one of claims 1 to 7 and thereafter curing the composition.

9. A method for producing a cured product, comprising B-staging the conductive resin composition according to any one of claims 1 to 7 at a temperature of 70 to 110°C and thereafter curing the composition at 130 to 250°C to produce the cured product.

The invention claimed is:

1. A conductive resin composition comprising:

(A) an epoxy resin,

(B) at least one compound having a (meth)acryloyl group and a glycidyl group,

(C) a phenolic resin curing agent,

(D) a radical polymerization initiator and

(E) a conductive particle,

wherein the number of moles of (meth)acryloyl groups in (B) is 7 to 28 with respect to the number of moles of the glycidyl groups in the conductive resin composition taken as 100.

2. The conductive resin composition according to claim 1, further comprising (F) a (meth)acrylate compound.

3. The conductive resin composition according to claim 2, wherein the total of the number of moles of the (meth)acryloyl groups in (B) and the number of moles of the (meth) acryloyl groups in (F) is 8 to 36 with respect to the number of moles of the glycidyl groups in the conductive resin composition taken as 100.

4. The conductive resin composition according to claim 2 further comprising (G) an amine curing catalyst.

5. The conductive resin composition according to claim 2, wherein (A) is a liquid epoxy resin.

6. The conductive resin composition according to claim 2, wherein (B) is a partially (meth)acrylated cresol novolak epoxy resin and/or a mono(meth)acrylated bisphenol epoxy resin.

7. The conductive resin composition according to claim 1, further comprising (G) an amine curing catalyst.

8. The conductive resin composition according to claim 1, wherein (A) is a liquid epoxy resin.

9. The conductive resin composition according to claim 1, wherein (B) is a partially (meth)acrylated cresol novolak epoxy resin and/or a mono (meth) acrylated bisphenol epoxy resin.

10. A cured product obtained by B-staging the conductive resin composition according to claim 1 and thereafter curing the composition.

11. A method for producing a cured product, comprising B-staging the conductive resin composition according to claim 1 at a temperature of 70 to 110° C. and thereafter curing the composition at 130 to 250° C. to produce the cured product.